

APPLICABLE STANDARD					
Rating	Operating Temperature Range	-55 °C to 85 °C (1)	Storage Temperature Range	-10 °C to 60 °C (2)	
	Voltage	100 V AC	Operating Humidity Range	40 % to 80 %	
	Current	0.4 A	Storage Humidity Range	40 % to 70 % (2)	
SPECIFICATIONS					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT
<b>CONSTRUCTION</b>					
General Examination	Visually and by measuring instrument.		According to drawing.	x	x
Marking	Confirmed visually.			x	x
<b>ELECTRIC CHARACTERISTICS</b>					
Contact Resistance	100 mA (DC or 1000 Hz).		45 mΩ MAX.	x	—
Contact Resistance Millivolt Level Method	20 mV MAX, 1mA(DC or 1000Hz)		55 mΩ MAX.	x	—
Insulation Resistance	250 V DC.		100 MΩ MIN.	x	—
Voltage Proof	300 V AC for 1 min.		No flashover or breakdown.	x	—
<b>MECHANICAL CHARACTERISTICS</b>					
Mechanical Operation	50 times insertions and extractions.		① Contact Resistance: 55 mΩ MAX. ② No damage, crack and looseness of parts.	x	—
Vibration	Frequency 10 to 55 Hz, amplitude: 1.5 mm, at 2 h for 3 directions.		① No electrical discontinuity of 1 μs. ② Contact Resistance: 55 mΩ MAX.	x	—
Shock	490 m/s <sup>2</sup> , duration of pulse 11 ms at 3 times for 3 directions.		③ No damage, crack and looseness of parts.	x	—
<b>ENVIRONMENTAL CHARACTERISTICS</b>					
Damp Heat (Steady State)	Exposed at 40±2 °C, 90 ~ 95 %, 96 h.		① Contact Resistance: 55 mΩ MAX. ② Insulation Resistance: 100 MΩ MIN.	x	—
Rapid Change of temperature	Temperature -55 → +85 °C Time 30 → 30 min under 5 cycles. (Relocation time to chamber : within 2~3 min)		③ No damage, crack and looseness of parts.	x	—
Corrosion Salt Mist	Exposed in 5 % salt water spray for 48 h.		① Contact Resistance: 55 mΩ MAX. ② No heavy corrosion.	x	—
Hydrogen Sulphide	Exposed in 3 PPM for 96 h. (Test standard: JEIDA-38)			x	—
Resistance to Soldering Heat	1) Reflow soldering Peak TMP : 250 °C MAX, Reflow TMP : 220 °C MIN for 60 sec 2) Soldering irons : 360 °C MAX for 5sec		No deformation of case of excessive looseness of the terminal.	x	—
Solderability	Soldered at solder temperature 240±3°C for immersion duration, 3 sec.		A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
REMARKS			APPROVED	HS. OKAWA	14. 05. 19
(1)Include temperature rise caused by current-carrying.			CHECKED	HT. YAMAGUCHI	14. 05. 19
(2)"Storage" means a long-term storage state for the unused product before assembly to PCB.			DESIGNED	KJ. NISHIWAKI	14. 05. 16
Unless otherwise specified, refer to JIS C 5402.			DRAWN	KJ. NISHIWAKI	14. 05. 16
Note	QT:Qualification Test AT:Assurance Test X:Applicable Test		DRAWING NO.	ELC4-150684-25	
	SPECIFICATION SHEET		PART NO.	FX8-60/60P11-SVJ (71)	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL578-0101-0-71	1/1

